Applicants' invention, in particular a composition including a non-reactive silicone fluid and 2/2003

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Applicants' invention, in particular a composition believed that the expectation that the having silica with the specific carbon contents and/or bulk density claimed by Applicants. Therefore, Applicants respectfully request that the Examiner reconsider her rejection that the present claims are prima facie obvious over the cited references and allow claims 1 to 20 to issue.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Respectfully submitted, Patricia M Siaduto

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## Version with markings to show changes made

## Claim 1 has been amended as follows:

- 1. (Amended Once) A water repellent silicone coating agent composition comprising
- (A) 100 parts by weight of diorganopolysiloxane having a viscosity of 20 to 20,000 mPa·s at 25°C in which the terminal ends of the molecular chain are blocked by silanol groups or siliconbonded hydrolyzable groups,
- (B) 5 to 100 parts by weight of a cross-linking agent represented by general formula R<sub>a</sub>SiX<sub>4-a</sub> in which R is a monovalent hydrocarbon group comprising 1 to 10 carbon atoms, X is a hydrolyzable group, and subscript a is an integer of 0 to 2,
- (C) 0.1 to 20 parts by weight of a condensation reaction catalyst,
- (D) 8 to 50 parts by weight of a hydrophobic surface treated dry process silica having a carbon content of 3.7 to 5% by weight and a bulk density of 40 to 99 g/L, or a hydrophobic surface treated dry process silica having a carbon content of 2.7 to 5% by weight and a bulk density of
- (E) 1 to 10 parts by weight of an organic functional silane coupling agent-based adhesion.
- (F) an organic solvent having a boiling point of 100 to 200°C in an amount of 4 to 100 wt% based on the total of component (A) to component (E), and [optionally]
- (G) 1 to 50 parts by weight of a non-reactive silicone fluid having a viscosity of 10 to 10,000 mPa·s at 25°C.